



N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	RDS(ON) Max	Ι _D Τ _A = +25°C		
20V	$0.4\Omega @ V_{GS} = 4.5V$	1A		
	0.7Ω @ V _{GS} = 1.8V	0.8A		

Features and Benefits

- Low On-Resistance
- Very Low Gate Threshold Voltage V_{GS(TH)}, 1.0V Max.
- Low Input Capacitance
- Fast Switching Speed
- Ultra-Small Surfaced Mount Package
- Ultra-Low Package Profile, 0.4mm Maximum Package Height
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

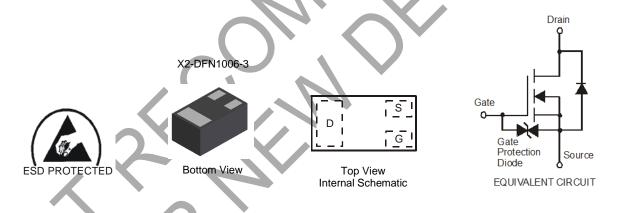
Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- DC-DC Converters
- Power Management Functions

Mechanical Data

- Case: X2-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish NiPdAu over Copper Leadframe; Solderable
 per MIL-STD-202, Method 208@4
 - Weight: 0.001 grams (Approximate)



Ordering Information (Note 4)

Part Number	Case	Packaging			
DMN2500UFB4-7	X2-DFN1006-3	3,000/Tape & Reel			
DMN2500UFB4-7B	X2-DFN1006-3	10,000/Tape & Reel			
Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.					

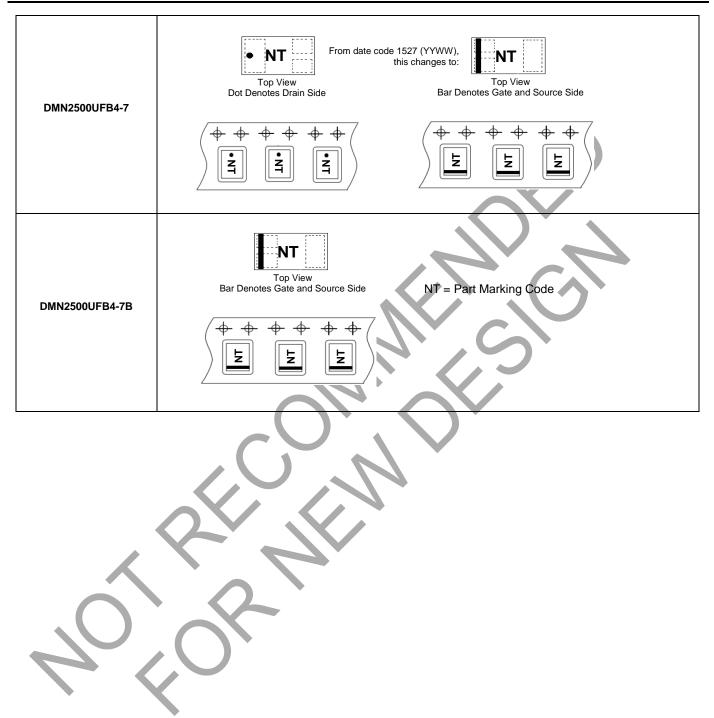
No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.</p>

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



Marking Information





Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit	
Drain-Source Voltage			V _{DSS}	20	V	
Gate-Source Voltage			V _{GSS}	±6	V	
Continuous Drain Current (Note 5) V_{GS} = 4.5V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	ID	810 640	mA	
	t<10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	950 750	mA	
Continuous Drain Current (Note 6) V_{GS} = 4.5V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	1000 800	mA	
	t<10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	ID	1200 1000	mA	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)		I _{DM}	4	А	
Maximum Body Diode Continuous Current			ls	850	mA	

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$ Steady State $t<10s$	P _D R _θ JA	0.46 0.29 279 210	• W °C/W °C/W
t<10s	R _θ JA		
	R _θ JA	210	°C/W
			0,
T _A = +25°C		0.95	14/
$T_A = +70^{\circ}C$ P_D		0.6	W
Steady State		134	°C/W
t<10s	R _{0JA}	100	°C/W
	T _J , T _{STG}	-55 to +150	°C
	T _A = +70°C Steady State	$T_A = +70^{\circ}C$ P_D Steady State $R_{\theta JA}$	$T_A = +70^{\circ}C$ P_D 0.6 Steady State134t<10s

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	20	-	-	V	$V_{GS} = 0V, I_D = 250 \mu A$	
Zero Gate Voltage Drain Current $T_J = +25^{\circ}C$	IDSS		-	100	nA	$V_{DS} = 20V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	-	-	±1.0	μA	$V_{GS} = \pm 4.5 V$, $V_{DS} = 0 V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	VGS(TH)	0.5	-	1.0	V	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	
			0.3	0.4	Ω	$V_{GS} = 4.5V, I_D = 600mA$	
Static Drain-Source On-Resistance	R _{DS(ON)}	-	0.4	0.5		$V_{GS} = 2.5V, I_D = 500mA$	
			0.5	0.7		$V_{GS} = 1.8V, I_{D} = 350mA$	
Forward Transfer Admittance	Y _{fs}	-	1.4	-	S	$V_{DS} = 10V, I_{D} = 400mA$	
Diode Forward Voltage	V _{SD}	-	0.7	1.2	V	$V_{GS} = 0V, I_{S} = 150mA$	
DYNAMIC CHARACTERISTICS (Note 8)	•						
Input Capacitance	Ciss	-	60.67	-	pF		
Output Capacitance	Coss	-	9.68	-	pF	V _{DS} =16V, V _{GS} = 0V, f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}	-	5.37	-	pF	1 = 1.00012	
Gate Resistance	Rg	-	93	-	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge	Qg	-	736.6	-	рС	$V_{GS} = 4.5V, V_{DS} = 10V,$ $I_D = 250mA$	
Gate-Source Charge	Qgs	-	93.6	-	рС		
Gate-Drain Charge	Q _{gd}	-	116.6	-	рС		
Turn-On Delay Time	t _{D(ON)}	-	5.1	-	ns	$V_{DD} = 10V, V_{GS} = 4.5V,$ $R_L = 47\Omega, R_G = 10\Omega,$ $I_D = 200mA$	
Turn-On Rise Time	t _R	-	7.4	-	ns		
Turn-Off Delay Time	t _{D(OFF)}	-	26.7	-	ns		
Turn-Off Fall Time	t _F	-	12.3	-	ns		

 Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate. Notes:

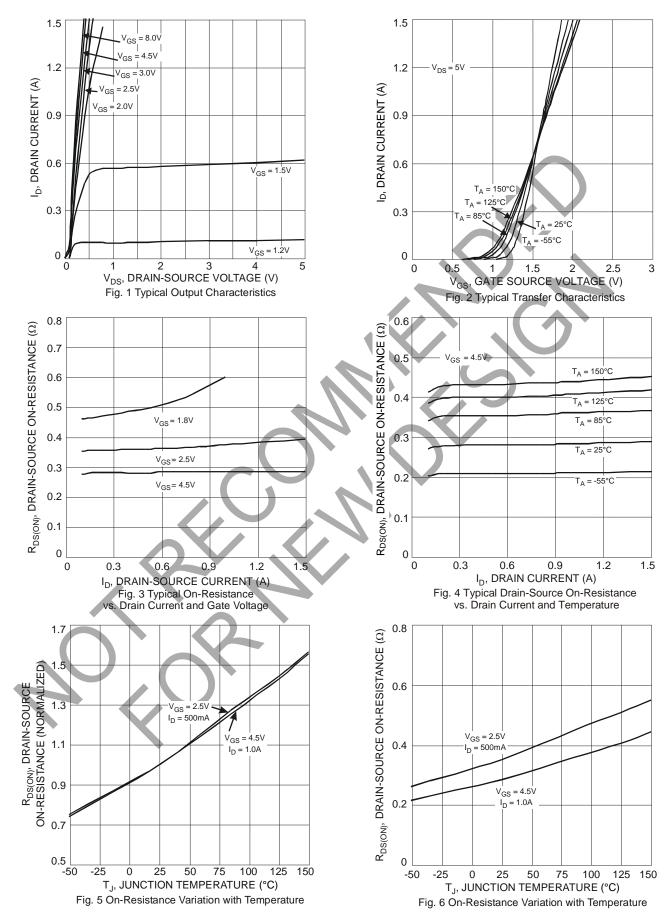
7. Short duration pulse test used to minimize self-heating effect.

8. Guaranteed by design. Not subject to product testing.



NOT RECOMMENDED FOR NEW DESIGN USE <u>DMN2450UFB4</u>

DMN2500UFB4

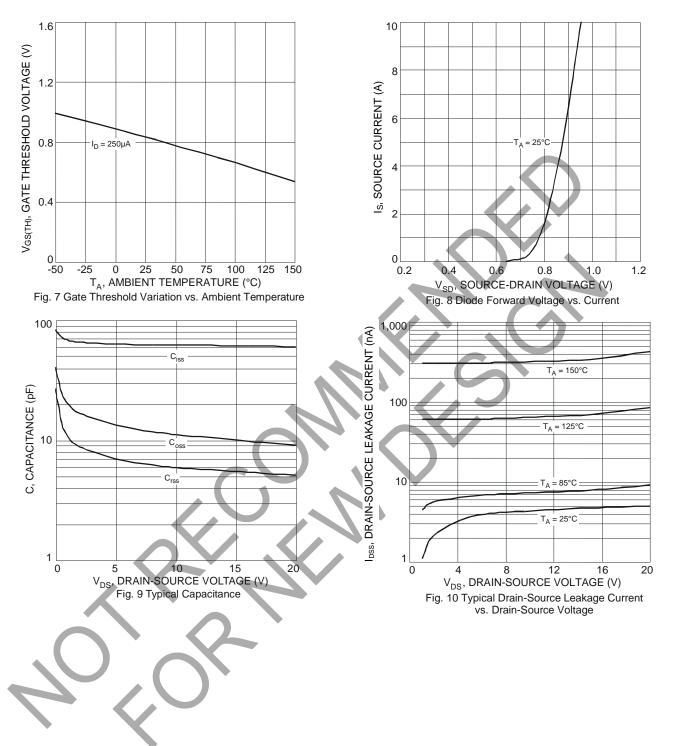


DMN2500UFB4 Document number: DS35724 Rev. 6 - 3



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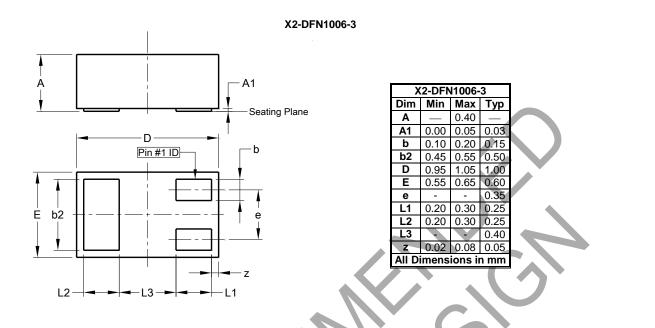
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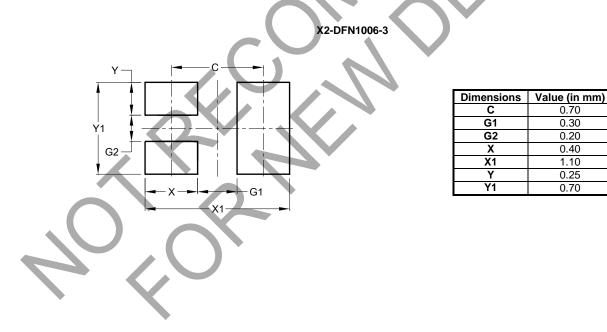
Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.



Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



0.30

0.20 0.40

1.10

0.25

0.70



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